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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Active
Number of LABs/CLBs	6036
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	171
Number of Gates	108000
Voltage - Supply	2.25V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TJ)
Package / Case	208-BFCQFP with Tie Bar
Supplier Device Package	208-CQFP (75x75)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/5962-0054301qyc

Temperature Grade Offering

Package	A54SX08A	A54SX16A	A54SX32A	A54SX72A
PQ208	C,I,A,M	C,I,A,M	C,I,A,M	C,I,A,M
TQ100	C,I,A,M	C,I,A,M	C,I,A,M	
TQ144	C,I,A,M	C,I,A,M	C,I,A,M	
TQ176			C,I,M	
BG329			C,I,M	
FG144	C,I,A,M	C,I,A,M	C,I,A,M	
FG256		C,I,A,M	C,I,A,M	C,I,A,M
FG484			C,I,M	C,I,A,M
CQ208			C,M,B	C,M,B
CQ256			C,M,B	C,M,B

Notes:

1. C = Commercial
2. I = Industrial
3. A = Automotive
4. M = Military
5. B = MIL-STD-883 Class B
6. For more information regarding automotive products, refer to the SX-A Automotive Family FPGAs datasheet.
7. For more information regarding Mil-Temp and ceramic packages, refer to the HiRel SX-A Family FPGAs datasheet.

Speed Grade and Temperature Grade Matrix

	F	Std	-1	-2	-3
Commercial	✓	✓	✓	✓	Discontinued
Industrial		✓	✓	✓	Discontinued
Automotive		✓			
Military		✓	✓		
MIL-STD-883B		✓	✓		

Notes:

1. For more information regarding automotive products, refer to the SX-A Automotive Family FPGAs datasheet.
2. For more information regarding Mil-Temp and ceramic packages, refer to the HiRel SX-A Family FPGAs datasheet.

Contact your Actel Sales representative for more information on availability.

General Description

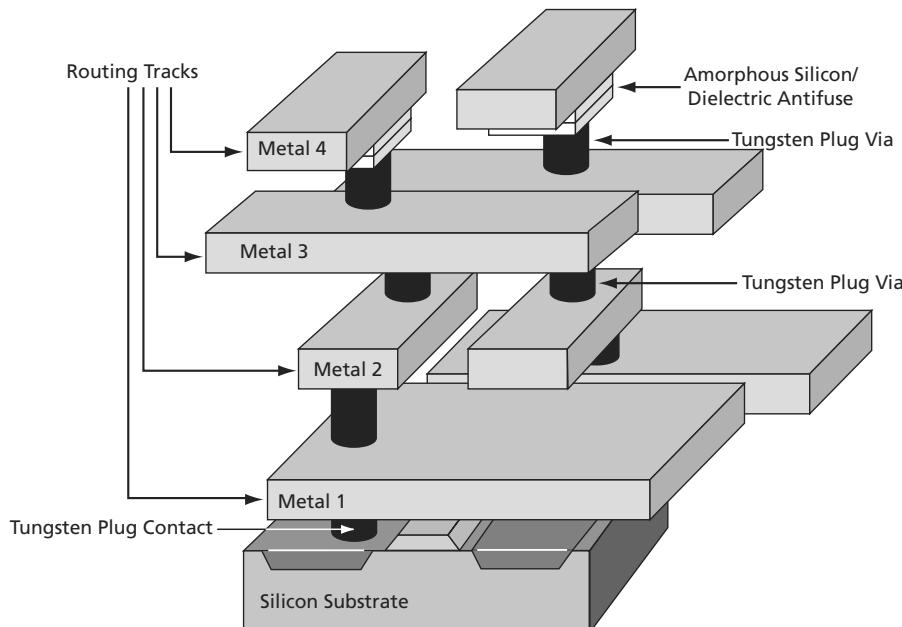
Introduction

The Actel SX-A family of FPGAs offers a cost-effective, single-chip solution for low-power, high-performance designs. Fabricated on $0.22\text{ }\mu\text{m} / 0.25\text{ }\mu\text{m}$ CMOS antifuse technology and with the support of 2.5 V, 3.3 V and 5 V I/Os, the SX-A is a versatile platform to integrate designs while significantly reducing time-to-market.

SX-A Family Architecture

The SX-A family's device architecture provides a unique approach to module organization and chip routing that satisfies performance requirements and delivers the most optimal register/logic mix for a wide variety of applications.

Interconnection between these logic modules is achieved using Actel's patented metal-to-metal programmable antifuses interconnect elements (Figure 1-1). The antifuses are normally open circuit and, when programmed, form a permanent low-impedance connection.



Note: The A54SX72A device has four layers of metal with the antifuse between Metal 3 and Metal 4. The A54SX08A, A54SX16A, and A54SX32A devices have three layers of metal with the antifuse between Metal 2 and Metal 3.

Figure 1-1 • SX-A Family Interconnect Elements

Guidelines for Estimating Power

The following guidelines are meant to represent worst-case scenarios; they can be generally used to predict the upper limits of power dissipation:

Logic Modules (m) = 20% of modules

Inputs Switching (n) = Number inputs/4

Outputs Switching (p) = Number of outputs/4

CLKA Loads (q1) = 20% of R-cells

CLKB Loads (q2) = 20% of R-cells

Load Capacitance (CL) = 35 pF

Average Logic Module Switching Rate (fm) = f/10

Average Input Switching Rate (fn) = f/5

Average Output Switching Rate (fp) = f/10

Average CLKA Rate (fq1) = f/2

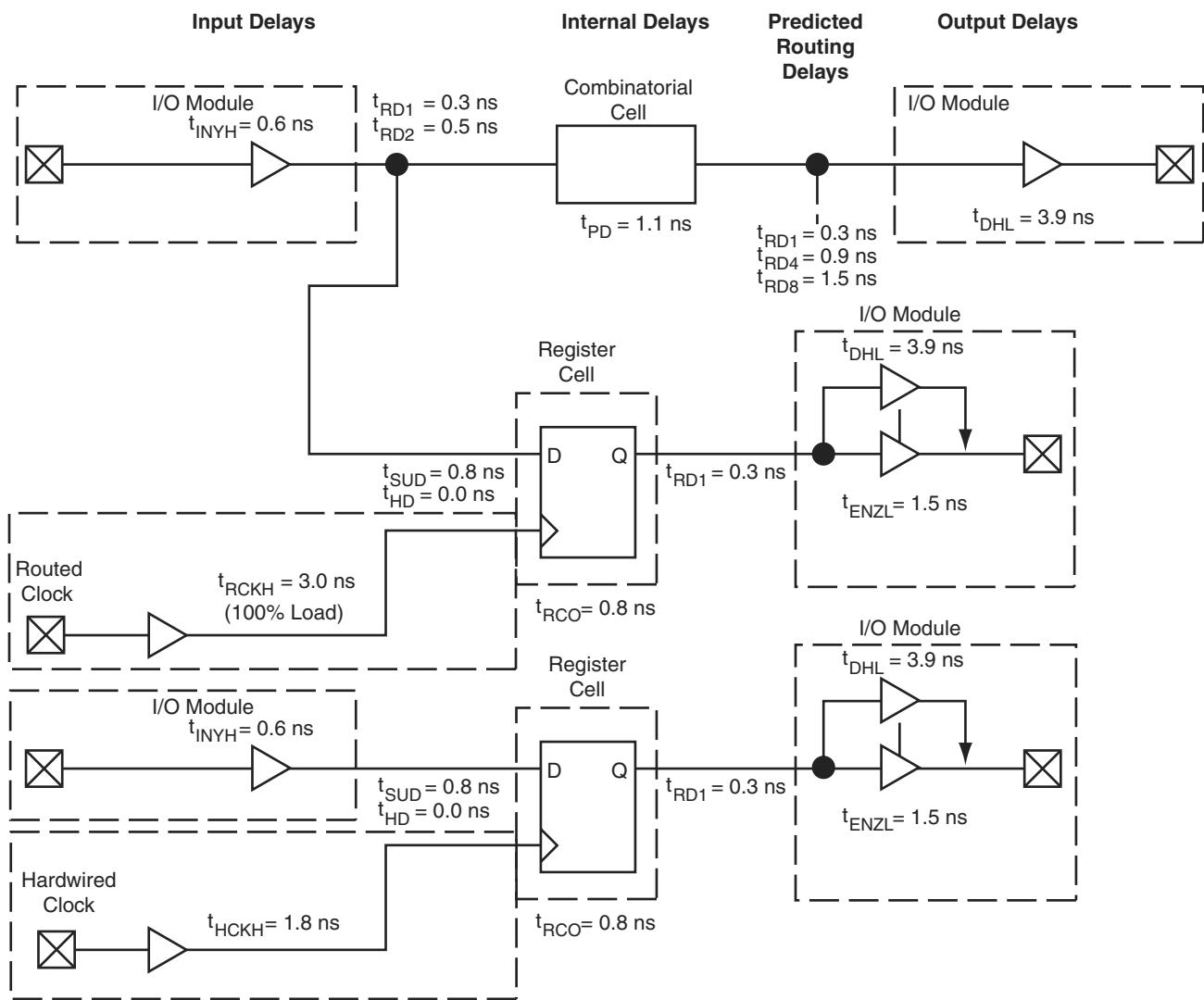
Average CLKB Rate (fq2) = f/2

Average HCLK Rate (fs1) = f

HCLK loads (s1) = 20% of R-cells

To assist customers in estimating the power dissipations of their designs, Actel has published the *eX, SX-A and RT54SX-S Power Calculator* worksheet.

SX-A Timing Model



Note: *Values shown for A54SX72A, -2, worst-case commercial conditions at 5 V PCI with standard place-and-route.

Figure 2-3 • SX-A Timing Model

Sample Path Calculations

Hardwired Clock

$$\begin{aligned}\text{External Setup} &= (t_{INYH} + t_{RD1} + t_{SUD}) - t_{HCKH} \\ &= 0.6 + 0.3 + 0.8 - 1.8 = -0.1 \text{ ns} \\ \text{Clock-to-Out (Pad-to-Pad)} &= t_{HCKH} + t_{RCO} + t_{RD1} + t_{DHL} \\ &= 1.8 + 0.8 + 0.3 + 3.9 = 6.8 \text{ ns}\end{aligned}$$

Routed Clock

$$\begin{aligned}\text{External Setup} &= (t_{INYH} + t_{RD1} + t_{SUD}) - t_{RCKH} \\ &= 0.6 + 0.3 + 0.8 - 3.0 = -1.3 \text{ ns} \\ \text{Clock-to-Out (Pad-to-Pad)} &= t_{RCKH} + t_{RCO} + t_{RD1} + t_{DHL} \\ &= 3.0 + 0.8 + 0.3 + 3.9 = 8.0 \text{ ns}\end{aligned}$$

Input Buffer Delays

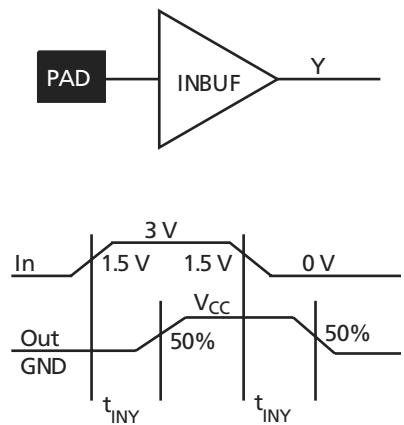


Figure 2-6 • Input Buffer Delays

C-Cell Delays

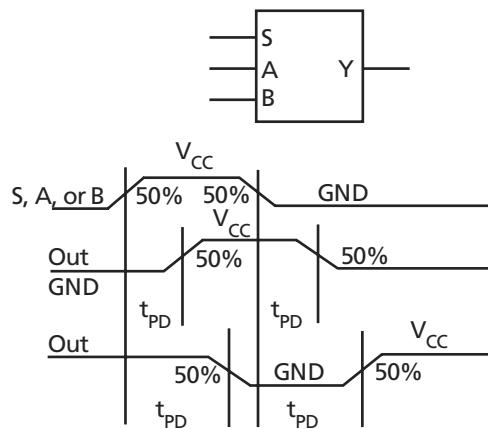


Figure 2-7 • C-Cell Delays

Cell Timing Characteristics

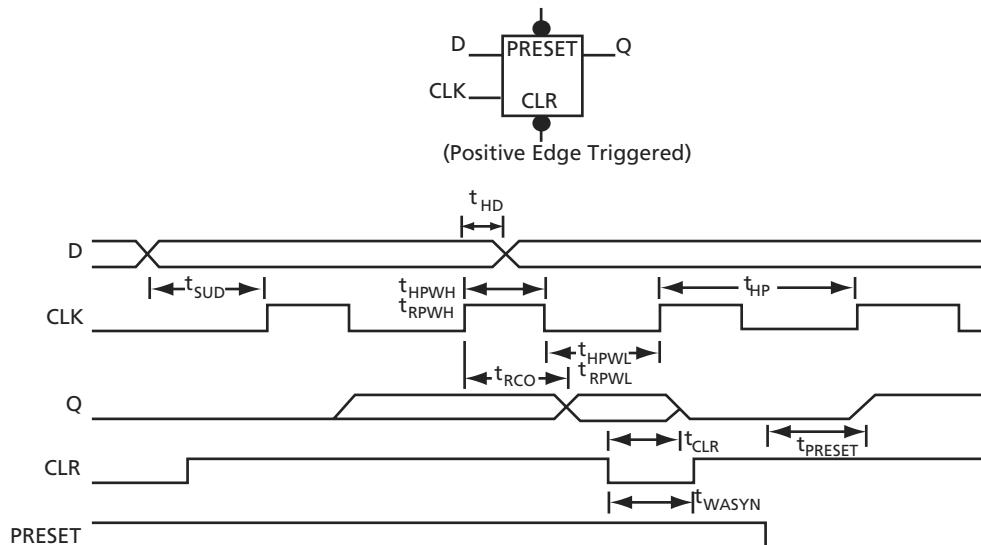


Figure 2-8 • Flip-Flops

Table 2-18 • A54SX08A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 2.3\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
2.5 V LVCMOS Output Module Timing^{1,2}										
t_{DLH}	Data-to-Pad Low to High	3.9	4.4	5.2	7.2	ns				
t_{DHL}	Data-to-Pad High to Low	3.0	3.4	3.9	5.5	ns				
t_{DHLS}	Data-to-Pad High to Low—low slew	13.3	15.1	17.7	24.8	ns				
t_{ENZL}	Enable-to-Pad, Z to L	2.8	3.2	3.7	5.2	ns				
t_{ENZLS}	Data-to-Pad, Z to L—low slew	13.7	15.5	18.2	25.5	ns				
t_{ENZH}	Enable-to-Pad, Z to H	3.9	4.4	5.2	7.2	ns				
t_{ENLZ}	Enable-to-Pad, L to Z	2.5	2.8	3.3	4.7	ns				
t_{ENHZ}	Enable-to-Pad, H to Z	3.0	3.4	3.9	5.5	ns				
d_{TLH}^3	Delta Low to High	0.037	0.043	0.051	0.071	ns/pF				
d_{THL}^3	Delta High to Low	0.017	0.023	0.023	0.037	ns/pF				
d_{THLS}^3	Delta High to Low—low slew	0.06	0.071	0.086	0.117	ns/pF				

Note:

1. Delays based on 35 pF loading.
2. The equivalent I/O Attribute Editor settings for 2.5 V LVCMOS is 2.5 V LVTTL in the software.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$
 where C_{load} is the load capacitance driven by the I/O in pF.
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.

Table 2-21 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹		-2 Speed		-1 Speed		Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
C-Cell Propagation Delays²										
t_{PD}	Internal Array Module	0.9	1.0	1.2	1.4	1.6	1.8	1.9	ns	
Predicted Routing Delays³										
t_{DC}	FO = 1 Routing Delay, Direct Connect	0.1	0.1	0.1	0.1	0.1	0.1	0.1	ns	
t_{FC}	FO = 1 Routing Delay, Fast Connect	0.3	0.3	0.3	0.4	0.4	0.4	0.6	ns	
t_{RD1}	FO = 1 Routing Delay	0.3	0.3	0.4	0.5	0.5	0.5	0.6	ns	
t_{RD2}	FO = 2 Routing Delay	0.4	0.5	0.5	0.6	0.6	0.6	0.8	ns	
t_{RD3}	FO = 3 Routing Delay	0.5	0.6	0.7	0.8	0.8	0.8	1.1	ns	
t_{RD4}	FO = 4 Routing Delay	0.7	0.8	0.9	1.0	1.0	1.0	1.4	ns	
t_{RD8}	FO = 8 Routing Delay	1.2	1.4	1.5	1.8	1.8	1.8	2.5	ns	
t_{RD12}	FO = 12 Routing Delay	1.7	2	2.2	2.6	2.6	2.6	3.6	ns	
R-Cell Timing										
t_{RCO}	Sequential Clock-to-Q	0.6	0.7	0.8	0.9	0.9	1.0	1.3	ns	
t_{CLR}	Asynchronous Clear-to-Q	0.5	0.6	0.6	0.8	0.8	1.0	1.0	ns	
t_{PRESET}	Asynchronous Preset-to-Q	0.7	0.8	0.8	1.0	1.0	1.4	1.4	ns	
t_{SUD}	Flip-Flop Data Input Set-Up	0.7	0.8	0.9	1.0	1.0	1.4	1.4	ns	
t_{HD}	Flip-Flop Data Input Hold	0.0	0.0	0.0	0.0	0.0	0.0	0.0	ns	
t_{WASYN}	Asynchronous Pulse Width	1.3	1.5	1.6	1.9	1.9	2.7	2.7	ns	
$t_{RECASYN}$	Asynchronous Recovery Time	0.3	0.4	0.4	0.5	0.5	0.7	0.7	ns	
t_{HASYN}	Asynchronous Removal Time	0.3	0.3	0.3	0.4	0.4	0.6	0.6	ns	
t_{MPW}	Clock Minimum Pulse Width	1.4	1.7	1.9	2.2	2.2	3.0	3.0	ns	
Input Module Propagation Delays										
t_{INYH}	Input Data Pad to Y High 2.5 V LVC MOS	0.5	0.6	0.7	0.8	0.8	1.1	1.1	ns	
t_{INYL}	Input Data Pad to Y Low 2.5 V LVC MOS	0.8	0.9	1.0	1.1	1.1	1.6	1.6	ns	
t_{INYH}	Input Data Pad to Y High 3.3 V PCI	0.5	0.6	0.6	0.7	0.7	1.0	1.0	ns	
t_{INYL}	Input Data Pad to Y Low 3.3 V PCI	0.7	0.8	0.9	1.0	1.0	1.4	1.4	ns	
t_{INYH}	Input Data Pad to Y High 3.3 V LV TTL	0.7	0.7	0.8	1.0	1.0	1.4	1.4	ns	
t_{INYL}	Input Data Pad to Y Low 3.3 V LV TTL	0.9	1.1	1.2	1.4	1.4	2.0	2.0	ns	

Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-21 • A54SX16A Timing Characteristics (Continued)
 (Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
t_{INYH}	Input Data Pad to Y High 5 V PCI	0.5	0.5	0.6	0.7	0.9	ns
t_{INYL}	Input Data Pad to Y Low 5 V PCI	0.7	0.8	0.9	1.1	1.5	ns
t_{IYH}	Input Data Pad to Y High 5 V TTL	0.5	0.5	0.6	0.7	0.9	ns
t_{IYL}	Input Data Pad to Y Low 5 V TTL	0.7	0.8	0.9	1.1	1.5	ns
Input Module Predicted Routing Delays²							
t_{IRD1}	FO = 1 Routing Delay	0.3	0.3	0.3	0.4	0.6	ns
t_{IRD2}	FO = 2 Routing Delay	0.4	0.5	0.5	0.6	0.8	ns
t_{IRD3}	FO = 3 Routing Delay	0.5	0.6	0.7	0.8	1.1	ns
t_{IRD4}	FO = 4 Routing Delay	0.7	0.8	0.9	1.0	1.4	ns
t_{IRD8}	FO = 8 Routing Delay	1.2	1.4	1.5	0.8	2.5	ns
t_{IRD12}	FO = 12 Routing Delay	1.7	2.0	2.2	2.6	3.6	ns

Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-27 • A54SX16A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
5 V PCI Output Module Timing²							
t_{DLH}	Data-to-Pad Low to High	2.2	2.5	2.8	3.3	4.6	ns
t_{DHL}	Data-to-Pad High to Low	2.8	3.2	3.6	4.2	5.9	ns
t_{ENZL}	Enable-to-Pad, Z to L	1.3	1.5	1.7	2.0	2.8	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.2	2.5	2.8	3.3	4.6	ns
t_{ENLZ}	Enable-to-Pad, L to Z	3.0	3.5	3.9	4.6	6.4	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.8	3.2	3.6	4.2	5.9	ns
d_{TLH}^3	Delta Low to High	0.016	0.016	0.02	0.022	0.032	ns/pF
d_{THL}^3	Delta High to Low	0.026	0.03	0.032	0.04	0.052	ns/pF
5 V TTL Output Module Timing⁴							
t_{DLH}	Data-to-Pad Low to High	2.2	2.5	2.8	3.3	4.6	ns
t_{DHL}	Data-to-Pad High to Low	2.8	3.2	3.6	4.2	5.9	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	6.7	7.7	8.7	10.2	14.3	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.1	2.4	2.7	3.2	4.5	ns
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	7.4	8.4	9.5	11.0	15.4	ns
t_{ENZH}	Enable-to-Pad, Z to H	1.9	2.2	2.5	2.9	4.1	ns
t_{ENLZ}	Enable-to-Pad, L to Z	3.6	4.2	4.7	5.6	7.8	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.5	2.9	3.3	3.9	5.4	ns
d_{TLH}^3	Delta Low to High	0.014	0.017	0.017	0.023	0.031	ns/pF
d_{THL}^3	Delta High to Low	0.023	0.029	0.031	0.037	0.051	ns/pF
d_{THLS}^3	Delta High to Low—low slew	0.043	0.046	0.057	0.066	0.089	ns/pF

Notes:

1. All -3 speed grades have been discontinued.
2. Delays based on 50 pF loading.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$

where C_{load} is the load capacitance driven by the I/O in pF
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
4. Delays based on 35 pF loading.

Table 2-28 • A54SX32A Timing Characteristics (Continued)
 (Worst-Case Commercial Conditions, $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
t_{INYH}	Input Data Pad to Y High 5 V PCI	0.7	0.8	0.9	1.0	1.4	ns
t_{INYL}	Input Data Pad to Y Low 5 V PCI	0.9	1.1	1.2	1.4	1.9	ns
t_{INYH}	Input Data Pad to Y High 5 V TTL	0.9	1.1	1.2	1.4	1.9	ns
t_{INYL}	Input Data Pad to Y Low 5 V TTL	1.4	1.6	1.8	2.1	2.9	ns
Input Module Predicted Routing Delays³							
t_{IRD1}	FO = 1 Routing Delay	0.3	0.3	0.3	0.4	0.6	ns
t_{IRD2}	FO = 2 Routing Delay	0.4	0.5	0.5	0.6	0.8	ns
t_{IRD3}	FO = 3 Routing Delay	0.5	0.6	0.7	0.8	1.1	ns
t_{IRD4}	FO = 4 Routing Delay	0.7	0.8	0.9	1	1.4	ns
t_{IRD8}	FO = 8 Routing Delay	1.2	1.4	1.5	1.8	2.5	ns
t_{IRD12}	FO = 12 Routing Delay	1.7	2	2.2	2.6	3.6	ns

Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use $t_{PD} + t_{RD1} + t_{PDn}$, $t_{RCO} + t_{RD1} + t_{PDn}$, or $t_{PD1} + t_{RD1} + t_{SUD}$, whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-30 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{HCKSW}	Maximum Skew	0.6	0.6	0.7	0.8	1.3	ns
t_{HP}	Minimum Period	2.8	3.2	3.6	4.2	5.8	ns
f_{HMAX}	Maximum Frequency	357	313	278	238	172	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	2.2	2.5	2.8	3.3	4.6	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	2.1	2.4	2.7	3.2	4.5	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	2.3	2.7	3.1	3.6	5	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	2.2	2.5	2.9	3.4	4.7	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	2.4	2.8	3.2	3.7	5.2	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.4	2.8	3.1	3.7	5.1	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{RCKSW}	Maximum Skew (Light Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (50% Load)	0.9	1.0	1.2	1.4	1.9	ns
t_{RCKSW}	Maximum Skew (100% Load)	0.9	1.0	1.2	1.4	1.9	ns

Note: *All -3 speed grades have been discontinued.

Table 2-31 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 4.75\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed*	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
Dedicated (Hardwired) Array Clock Networks							
t_{HCKH}	Input Low to High (Pad to R-cell Input)	1.7	1.9	2.2	2.6	4.0	ns
t_{HCKL}	Input High to Low (Pad to R-cell Input)	1.7	2.0	2.2	2.6	4.0	ns
t_{HPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{HPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{HCKSW}	Maximum Skew	0.6	0.6	0.7	0.8	1.3	ns
t_{HP}	Minimum Period	2.8	3.2	3.6	4.2	5.8	ns
f_{HMAX}	Maximum Frequency	357	313	278	238	172	MHz
Routed Array Clock Networks							
t_{RCKH}	Input Low to High (Light Load) (Pad to R-cell Input)	2.2	2.5	2.8	3.3	4.7	ns
t_{RCKL}	Input High to Low (Light Load) (Pad to R-cell Input)	2.1	2.5	2.8	3.3	4.5	ns
t_{RCKH}	Input Low to High (50% Load) (Pad to R-cell Input)	2.4	2.7	3.1	3.6	5.1	ns
t_{RCKL}	Input High to Low (50% Load) (Pad to R-cell Input)	2.2	2.6	2.9	3.4	4.7	ns
t_{RCKH}	Input Low to High (100% Load) (Pad to R-cell Input)	2.5	2.8	3.2	3.8	5.3	ns
t_{RCKL}	Input High to Low (100% Load) (Pad to R-cell Input)	2.4	2.8	3.1	3.7	5.2	ns
t_{RPWH}	Minimum Pulse Width High	1.4	1.6	1.8	2.1	2.9	ns
t_{RPWL}	Minimum Pulse Width Low	1.4	1.6	1.8	2.1	2.9	ns
t_{RCKSW}	Maximum Skew (Light Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (50% Load)	1.0	1.1	1.3	1.5	2.1	ns
t_{RCKSW}	Maximum Skew (100% Load)	1.0	1.1	1.3	1.5	2.1	ns

Note: *All -3 speed grades have been discontinued.

Table 2-33 • A54SX32A Timing Characteristics
 (Worst-Case Commercial Conditions $V_{CCA} = 2.25\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$)

Parameter	Description	-3 Speed¹	-2 Speed	-1 Speed	Std. Speed	-F Speed	Units
		Min.	Max.	Min.	Max.	Min.	
3.3 V PCI Output Module Timing²							
t_{DLH}	Data-to-Pad Low to High	1.9	2.2	2.4	2.9	4.0	ns
t_{DHL}	Data-to-Pad High to Low	2.0	2.3	2.6	3.1	4.3	ns
t_{ENZL}	Enable-to-Pad, Z to L	1.4	1.7	1.9	2.2	3.1	ns
t_{ENZH}	Enable-to-Pad, Z to H	1.9	2.2	2.4	2.9	4.0	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.5	2.8	3.2	3.8	5.3	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.0	2.3	2.6	3.1	4.3	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
3.3 V LVTTL Output Module Timing⁴							
t_{DLH}	Data-to-Pad Low to High	2.6	3.0	3.4	4.0	5.6	ns
t_{DHL}	Data-to-Pad High to Low	2.6	3.0	3.3	3.9	5.5	ns
t_{DHLS}	Data-to-Pad High to Low—low slew	9.0	10.4	11.8	13.8	19.3	ns
t_{ENZL}	Enable-to-Pad, Z to L	2.2	2.6	2.9	3.4	4.8	ns
t_{ENZLS}	Enable-to-Pad, Z to L—low slew	15.8	18.9	21.3	25.4	34.9	ns
t_{ENZH}	Enable-to-Pad, Z to H	2.6	3.0	3.4	4.0	5.6	ns
t_{ENLZ}	Enable-to-Pad, L to Z	2.9	3.3	3.7	4.4	6.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z	2.6	3.0	3.3	3.9	5.5	ns
d_{TLH}^3	Delta Low to High	0.025	0.03	0.03	0.04	0.045	ns/pF
d_{THL}^3	Delta High to Low	0.015	0.015	0.015	0.015	0.025	ns/pF
d_{THLS}^3	Delta High to Low—low slew	0.053	0.053	0.067	0.073	0.107	ns/pF

Notes:

1. All -3 speed grades have been discontinued.
2. Delays based on 10 pF loading and 25 Ω resistance.
3. To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the V_{CCI} value into the following equation:

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[LH|HL|HLS]})$$

where C_{load} is the load capacitance driven by the I/O in pF.
 $d_{T[LH|HL|HLS]}$ is the worst case delta value from the datasheet in ns/pF.
4. Delays based on 35 pF loading.

144-Pin TQFP

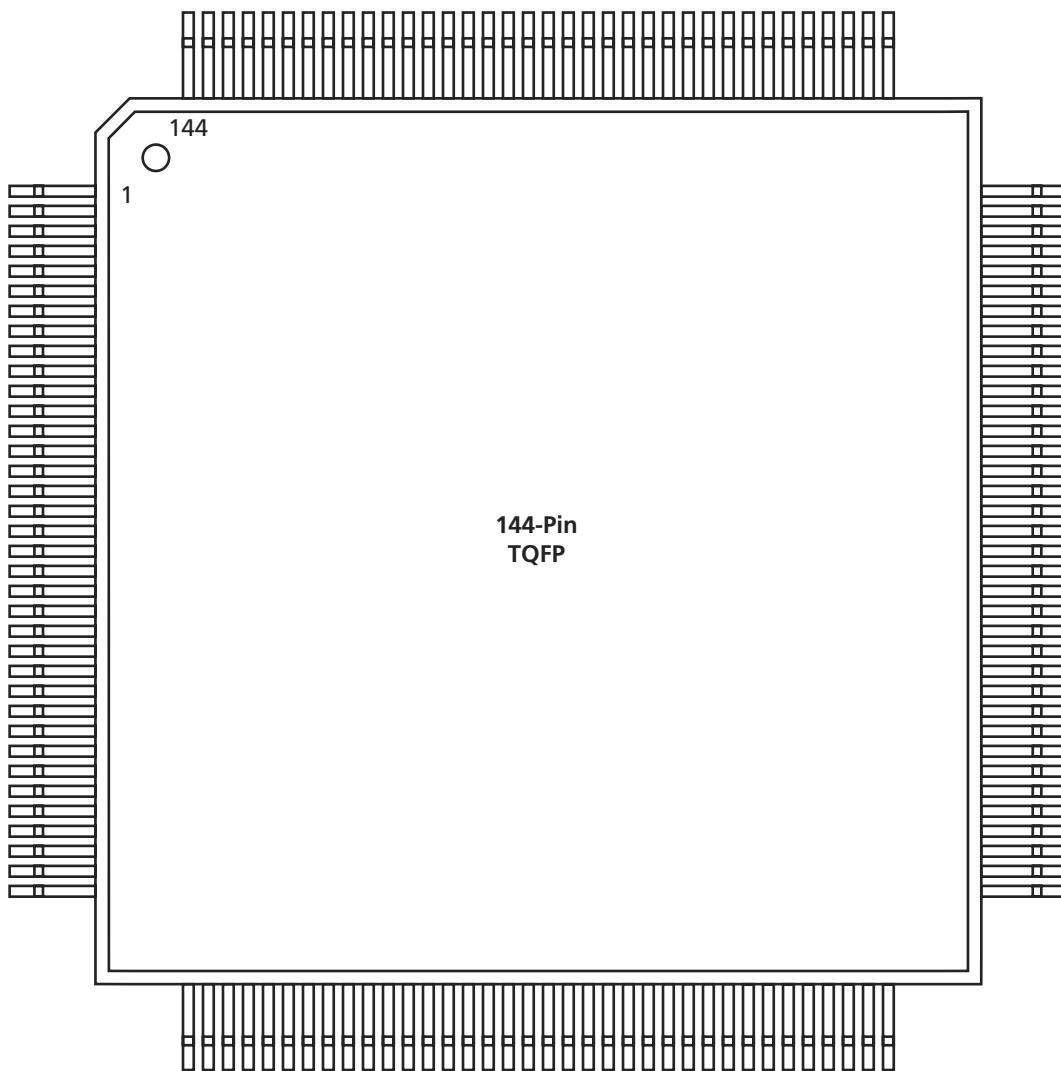


Figure 3-3 • 144-Pin TQFP (Top View)

Note

For Package Manufacturing and Environmental information, visit Resource center at
<http://www.actel.com/products/rescenter/package/index.html>.

176-Pin TQFP	
Pin Number	A54SX32A Function
1	GND
2	TDI, I/O
3	I/O
4	I/O
5	I/O
6	I/O
7	I/O
8	I/O
9	I/O
10	TMS
11	V _{CC1}
12	I/O
13	I/O
14	I/O
15	I/O
16	I/O
17	I/O
18	I/O
19	I/O
20	I/O
21	GND
22	V _{CCA}
23	GND
24	I/O
25	TRST, I/O
26	I/O
27	I/O
28	I/O
29	I/O
30	I/O
31	I/O
32	V _{CC1}
33	V _{CCA}
34	I/O
35	I/O
36	I/O

176-Pin TQFP	
Pin Number	A54SX32A Function
37	I/O
38	I/O
39	I/O
40	I/O
41	I/O
42	I/O
43	I/O
44	GND
45	I/O
46	I/O
47	I/O
48	I/O
49	I/O
50	I/O
51	I/O
52	V _{CC1}
53	I/O
54	I/O
55	I/O
56	I/O
57	I/O
58	I/O
59	I/O
60	I/O
61	I/O
62	I/O
63	I/O
64	PRB, I/O
65	GND
66	V _{CCA}
67	NC
68	I/O
69	HCLK
70	I/O
71	I/O
72	I/O

176-Pin TQFP	
Pin Number	A54SX32A Function
73	I/O
74	I/O
75	I/O
76	I/O
77	I/O
78	I/O
79	I/O
80	I/O
81	I/O
82	V _{CC1}
83	I/O
84	I/O
85	I/O
86	I/O
87	TDO, I/O
88	I/O
89	GND
90	I/O
91	I/O
92	I/O
93	I/O
94	I/O
95	I/O
96	I/O
97	I/O
98	V _{CCA}
99	V _{CC1}
100	I/O
101	I/O
102	I/O
103	I/O
104	I/O
105	I/O
106	I/O
107	I/O
108	GND

176-Pin TQFP	
Pin Number	A54SX32A Function
109	V _{CCA}
110	GND
111	I/O
112	I/O
113	I/O
114	I/O
115	I/O
116	I/O
117	I/O
118	I/O
119	I/O
120	I/O
121	I/O
122	V _{CCA}
123	GND
124	V _{CC1}
125	I/O
126	I/O
127	I/O
128	I/O
129	I/O
130	I/O
131	I/O
132	I/O
133	GND
134	I/O
135	I/O
136	I/O
137	I/O
138	I/O
139	I/O
140	V _{CC1}
141	I/O
142	I/O
143	I/O
144	I/O

329-Pin PBGA	
Pin Number	A54SX32A Function
D11	V _{CCA}
D12	NC
D13	I/O
D14	I/O
D15	I/O
D16	I/O
D17	I/O
D18	I/O
D19	I/O
D20	I/O
D21	I/O
D22	I/O
D23	I/O
E1	V _{CCI}
E2	I/O
E3	I/O
E4	I/O
E20	I/O
E21	I/O
E22	I/O
E23	I/O
F1	I/O
F2	TMS
F3	I/O
F4	I/O
F20	I/O
F21	I/O
F22	I/O
F23	I/O
G1	I/O
G2	I/O
G3	I/O
G4	I/O
G20	I/O
G21	I/O
G22	I/O
G23	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
H1	I/O
H2	I/O
H3	I/O
H4	I/O
H20	V _{CCA}
H21	I/O
H22	I/O
H23	I/O
J1	NC
J2	I/O
J3	I/O
J4	I/O
J20	I/O
J21	I/O
J22	I/O
J23	I/O
K1	I/O
K2	I/O
K3	I/O
K4	I/O
K10	GND
K11	GND
K12	GND
K13	GND
K14	GND
K20	I/O
K21	I/O
K22	I/O
K23	I/O
L1	I/O
L2	I/O
L3	I/O
L4	NC
L10	GND
L11	GND
L12	GND
L13	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
L14	GND
L20	NC
L21	I/O
L22	I/O
L23	NC
M1	I/O
M2	I/O
M3	I/O
M4	V _{CCA}
M10	GND
M11	GND
M12	GND
M13	GND
M14	GND
M20	V _{CCA}
M21	I/O
M22	I/O
M23	V _{CCI}
N1	I/O
N2	TRST, I/O
N3	I/O
N4	I/O
N10	GND
N11	GND
N12	GND
N13	GND
N14	GND
N20	NC
N21	I/O
N22	I/O
N23	I/O
P1	I/O
P2	I/O
P3	I/O
P4	I/O
P10	GND
P11	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
P12	GND
P13	GND
P14	GND
P20	I/O
P21	I/O
P22	I/O
P23	I/O
R1	I/O
R2	I/O
R3	I/O
R4	I/O
R20	I/O
R21	I/O
R22	I/O
R23	I/O
T1	I/O
T2	I/O
T3	I/O
T4	I/O
T20	I/O
T21	I/O
T22	I/O
T23	I/O
U1	I/O
U2	I/O
U3	V _{CCA}
U4	I/O
U20	I/O
U21	V _{CCA}
U22	I/O
U23	I/O
V1	V _{CCI}
V2	I/O
V3	I/O
V4	I/O
V20	I/O
V21	I/O

144-Pin FBGA

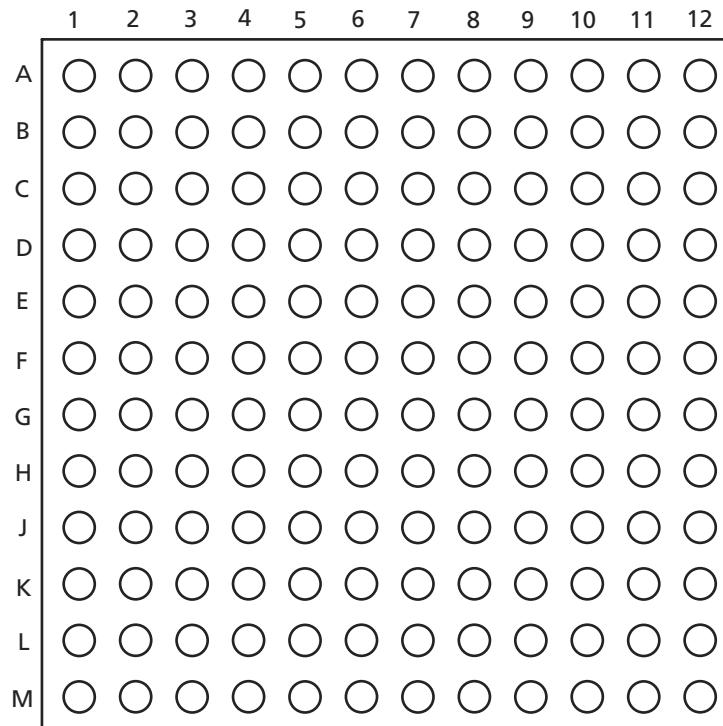


Figure 3-6 • 144-Pin FBGA (Top View)

Note

For Package Manufacturing and Environmental information, visit Resource center at
<http://www.actel.com/products/rescenter/package/index.html>.

144-Pin FBGA			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
A1	I/O	I/O	I/O
A2	I/O	I/O	I/O
A3	I/O	I/O	I/O
A4	I/O	I/O	I/O
A5	V _{CCA}	V _{CCA}	V _{CCA}
A6	GND	GND	GND
A7	CLKA	CLKA	CLKA
A8	I/O	I/O	I/O
A9	I/O	I/O	I/O
A10	I/O	I/O	I/O
A11	I/O	I/O	I/O
A12	I/O	I/O	I/O
B1	I/O	I/O	I/O
B2	GND	GND	GND
B3	I/O	I/O	I/O
B4	I/O	I/O	I/O
B5	I/O	I/O	I/O
B6	I/O	I/O	I/O
B7	CLKB	CLKB	CLKB
B8	I/O	I/O	I/O
B9	I/O	I/O	I/O
B10	I/O	I/O	I/O
B11	GND	GND	GND
B12	I/O	I/O	I/O
C1	I/O	I/O	I/O
C2	I/O	I/O	I/O
C3	TCK, I/O	TCK, I/O	TCK, I/O
C4	I/O	I/O	I/O
C5	I/O	I/O	I/O
C6	PRA, I/O	PRA, I/O	PRA, I/O
C7	I/O	I/O	I/O
C8	I/O	I/O	I/O
C9	I/O	I/O	I/O
C10	I/O	I/O	I/O
C11	I/O	I/O	I/O
C12	I/O	I/O	I/O

144-Pin FBGA			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
D1	I/O	I/O	I/O
D2	V _{CCI}	V _{CCI}	V _{CCI}
D3	TDI, I/O	TDI, I/O	TDI, I/O
D4	I/O	I/O	I/O
D5	I/O	I/O	I/O
D6	I/O	I/O	I/O
D7	I/O	I/O	I/O
D8	I/O	I/O	I/O
D9	I/O	I/O	I/O
D10	I/O	I/O	I/O
D11	I/O	I/O	I/O
D12	I/O	I/O	I/O
E1	I/O	I/O	I/O
E2	I/O	I/O	I/O
E3	I/O	I/O	I/O
E4	I/O	I/O	I/O
E5	TMS	TMS	TMS
E6	V _{CCI}	V _{CCI}	V _{CCI}
E7	V _{CCI}	V _{CCI}	V _{CCI}
E8	V _{CCI}	V _{CCI}	V _{CCI}
E9	V _{CCA}	V _{CCA}	V _{CCA}
E10	I/O	I/O	I/O
E11	GND	GND	GND
E12	I/O	I/O	I/O
F1	I/O	I/O	I/O
F2	I/O	I/O	I/O
F3	NC	NC	NC
F4	I/O	I/O	I/O
F5	GND	GND	GND
F6	GND	GND	GND
F7	GND	GND	GND
F8	V _{CCI}	V _{CCI}	V _{CCI}
F9	I/O	I/O	I/O
F10	GND	GND	GND
F11	I/O	I/O	I/O
F12	I/O	I/O	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
K5	I/O	I/O	I/O
K6	V _{CCI}	V _{CCI}	V _{CCI}
K7	GND	GND	GND
K8	GND	GND	GND
K9	GND	GND	GND
K10	GND	GND	GND
K11	V _{CCI}	V _{CCI}	V _{CCI}
K12	I/O	I/O	I/O
K13	I/O	I/O	I/O
K14	I/O	I/O	I/O
K15	NC	I/O	I/O
K16	I/O	I/O	I/O
L1	I/O	I/O	I/O
L2	I/O	I/O	I/O
L3	I/O	I/O	I/O
L4	I/O	I/O	I/O
L5	I/O	I/O	I/O
L6	I/O	I/O	I/O
L7	V _{CCI}	V _{CCI}	V _{CCI}
L8	V _{CCI}	V _{CCI}	V _{CCI}
L9	V _{CCI}	V _{CCI}	V _{CCI}
L10	V _{CCI}	V _{CCI}	V _{CCI}
L11	I/O	I/O	I/O
L12	I/O	I/O	I/O
L13	I/O	I/O	I/O
L14	I/O	I/O	I/O
L15	I/O	I/O	I/O
L16	NC	I/O	I/O
M1	I/O	I/O	I/O
M2	I/O	I/O	I/O
M3	I/O	I/O	I/O
M4	I/O	I/O	I/O
M5	I/O	I/O	I/O
M6	I/O	I/O	I/O
M7	I/O	I/O	QCLKA
M8	PRB, I/O	PRB, I/O	PRB, I/O
M9	I/O	I/O	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
M10	I/O	I/O	I/O
M11	I/O	I/O	I/O
M12	NC	I/O	I/O
M13	I/O	I/O	I/O
M14	NC	I/O	I/O
M15	I/O	I/O	I/O
M16	I/O	I/O	I/O
N1	I/O	I/O	I/O
N2	I/O	I/O	I/O
N3	I/O	I/O	I/O
N4	I/O	I/O	I/O
N5	I/O	I/O	I/O
N6	I/O	I/O	I/O
N7	I/O	I/O	I/O
N8	I/O	I/O	I/O
N9	I/O	I/O	I/O
N10	I/O	I/O	I/O
N11	I/O	I/O	I/O
N12	I/O	I/O	I/O
N13	I/O	I/O	I/O
N14	I/O	I/O	I/O
N15	I/O	I/O	I/O
N16	I/O	I/O	I/O
P1	I/O	I/O	I/O
P2	GND	GND	GND
P3	I/O	I/O	I/O
P4	I/O	I/O	I/O
P5	NC	I/O	I/O
P6	I/O	I/O	I/O
P7	I/O	I/O	I/O
P8	I/O	I/O	I/O
P9	I/O	I/O	I/O
P10	NC	I/O	I/O
P11	I/O	I/O	I/O
P12	I/O	I/O	I/O
P13	V _{CCA}	V _{CCA}	V _{CCA}
P14	I/O	I/O	I/O

256-Pin FBGA			
Pin Number	A54SX16A Function	A54SX32A Function	A54SX72A Function
P15	I/O	I/O	I/O
P16	I/O	I/O	I/O
R1	I/O	I/O	I/O
R2	GND	GND	GND
R3	I/O	I/O	I/O
R4	NC	I/O	I/O
R5	I/O	I/O	I/O
R6	I/O	I/O	I/O
R7	I/O	I/O	I/O
R8	I/O	I/O	I/O
R9	HCLK	HCLK	HCLK
R10	I/O	I/O	QCLKB
R11	I/O	I/O	I/O
R12	I/O	I/O	I/O
R13	I/O	I/O	I/O
R14	I/O	I/O	I/O
R15	GND	GND	GND
R16	GND	GND	GND
T1	GND	GND	GND
T2	I/O	I/O	I/O
T3	I/O	I/O	I/O
T4	NC	I/O	I/O
T5	I/O	I/O	I/O
T6	I/O	I/O	I/O
T7	I/O	I/O	I/O
T8	I/O	I/O	I/O
T9	V _{CCA}	V _{CCA}	V _{CCA}
T10	I/O	I/O	I/O
T11	I/O	I/O	I/O
T12	NC	I/O	I/O
T13	I/O	I/O	I/O
T14	I/O	I/O	I/O
T15	TDO, I/O	TDO, I/O	TDO, I/O
T16	GND	GND	GND